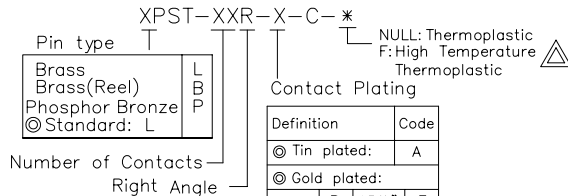


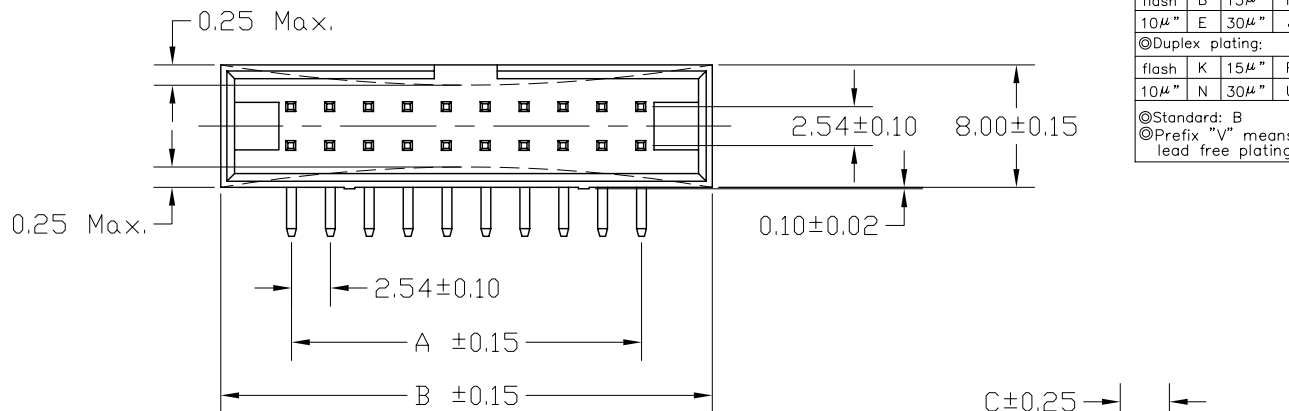
	A	B	REMARK (備註)
10	10.16	19.30	⊕
20	22.86	32.00	⊕



Definition	Code
◎ Tin plated:	A
◎ Gold plated:	
flash B 15μ"	F
10μ" E 30μ"	J
◎ Duplex plating:	
flash K 15μ"	P
10μ" N 30μ"	U
◎ Standard: B	
◎ Prefix "V" means lead free plating.	

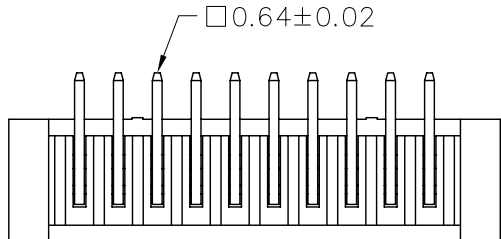
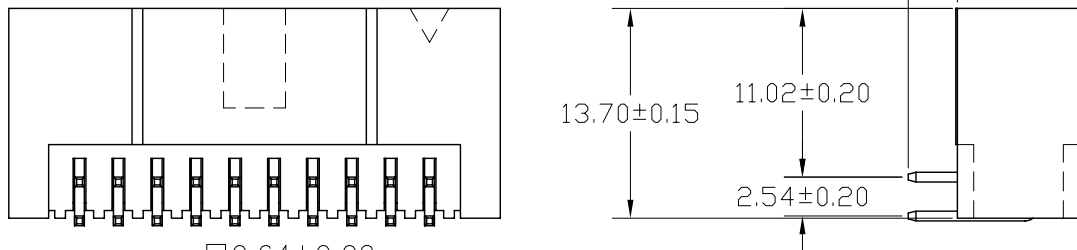
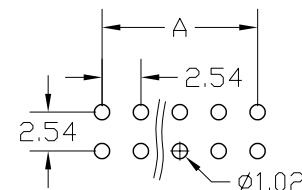
SPECIFICATIONS

Current Rating: 3 Amps
 Insulator resistance: 5000 Megohms min.
 Dielectric withstanding: AC 1000 V
 Operating Temperature: -40°~+105°C
 Contact Material: Copper alloy
 Insulator Material: Thermoplastic, UL 94V-0
 Color: Black
 Finish: Tin, Gold or Duplex plated
 ◎ Standard: Gold flash all over
 ◎ Note: Duplex plating: gold plated on contact area, Tin on solder area



◎ For illustration purpose the XPST-XXR-X-032 was shown

Recommended PCB Layout
(PCB TOLERANCE ±0.05)



PARTS NO.	C	REMARK (備註)
XPST-XXR-X-032	3.20	○

Diagram	Molding description	Rev.	ECN Number	Description	Drawn	Date
○	mass production & assemble mold	2	ECR-540099	修正開模備註	陳美竹	04/20 05'
◎	sample & assemble mold	3	EC2-580202	新增耐高溫材質	陳顯鑫	08/29 05'
⊕	mass production & fix mold					
⊕	sample & fix mold					



GENERAL TOLERANCE	
XX. ± 0.50	XXX. ±
X. ± 0.30	.XXX ±
.X ± 0.25	.X° ± 4°
.XX ± 0.20	.X° ± 4°

SCALE	2=1
UNIT	MM
SIZE	A4

ORIGINAL DRAWN	邱若婷	DATE	01/22 03'
CHECK	林錫錦	DATE	08/29 05'
APPROVE	林錫錦	DATE	08/29 05'

DWG. NO.	X-XX
TITLE	2.54mm SHOULDED HEADER (成品規格圖)

DATE	01/22 03'
DATE	08/29 05'
DATE	08/29 05'
PARTS NO.	XPST-XXR-X-C

REV.	3
SHEET	1/1